

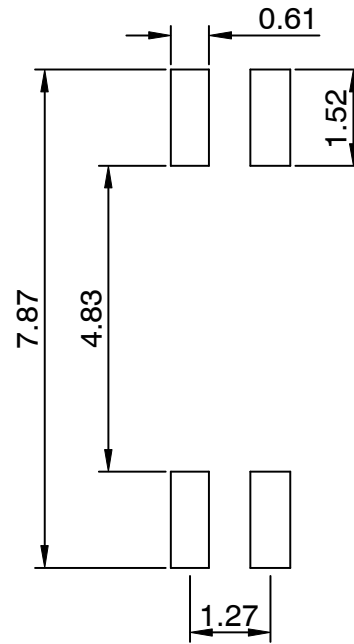
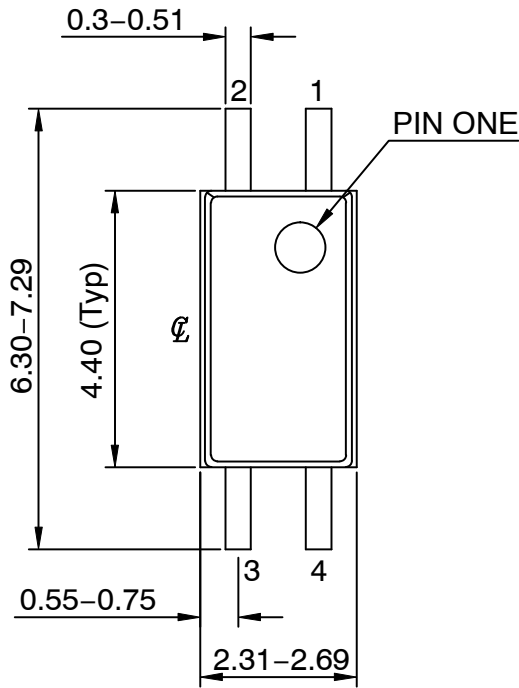
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

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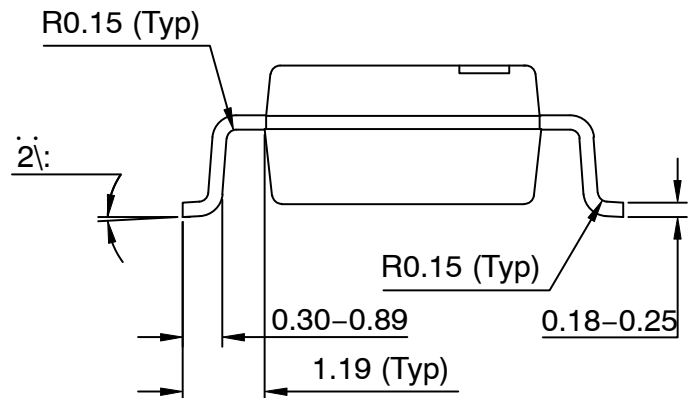
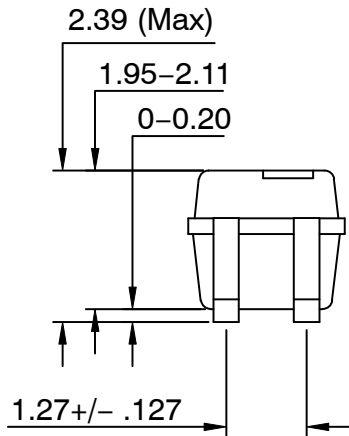


MFP4 2.5X4.4, 1.27P
CASE 100AL
ISSUE O

DATE 31 AUG 2016



LAND PATTERN RECOMMENDATION



NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION

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